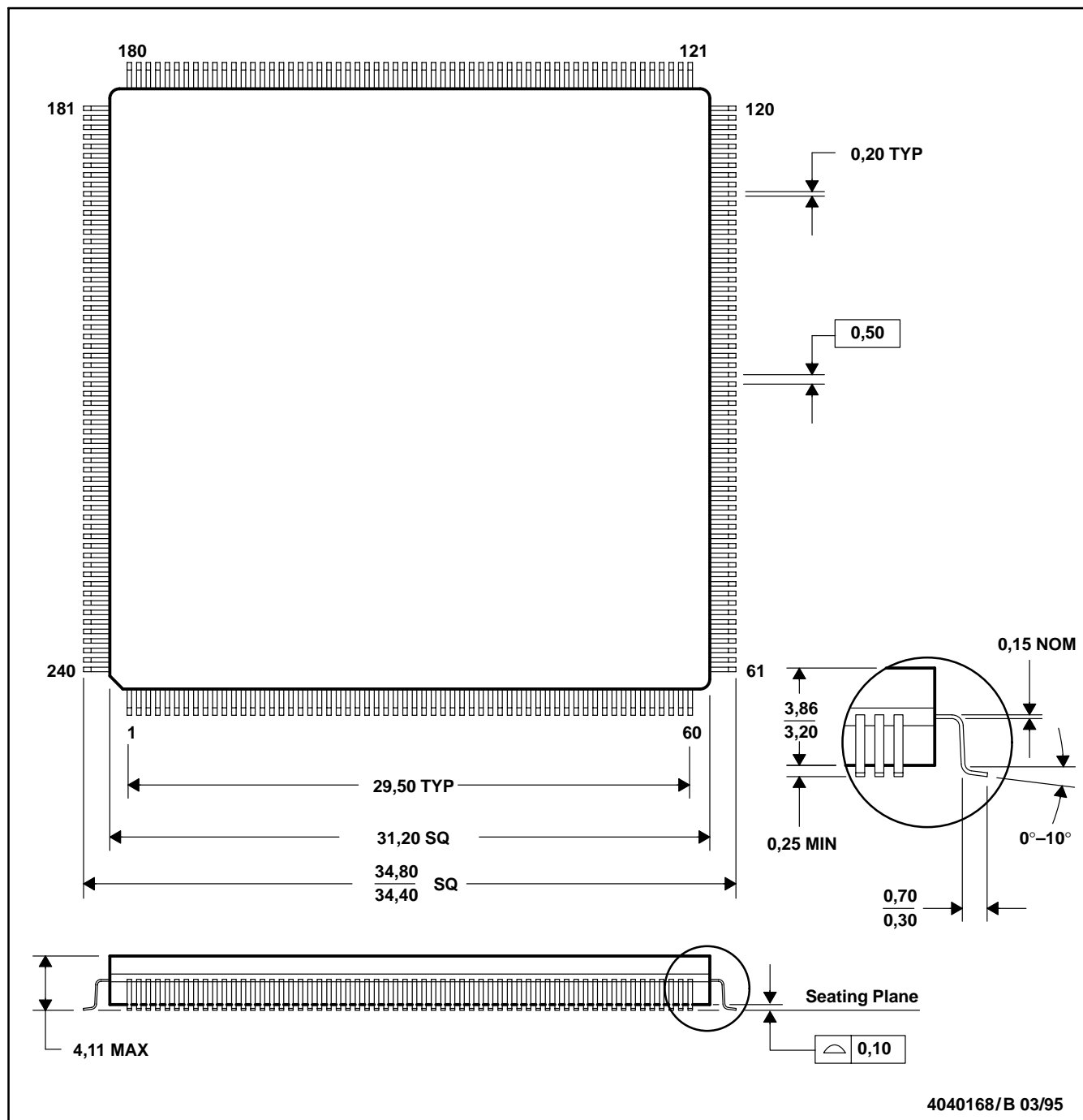


WH (S-GQFP-G240)

CERAMIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Ceramic material is ALN.

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